MMBT2907ALT1

General Purpose Transistors

PNP Silicon

Features

- Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	-60	Vdc
Collector-Base Voltage	V_{CBO}	-60	Vdc
Emitter-Base Voltage	V_{EBO}	-5.0	Vdc
Collector Current - Continuous	I_C	-600	mAdc
Collector Current - Peak (Note 3)	I_{CM}	-1200	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T_A = 25°C Derate above 25°C	P_D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) @T_A = 25°C Derate above 25°C	P_D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
1. FR-5 = 1.0 × 0.75 × 0.062 in.
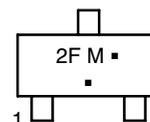2. Alumina = 0.4 × 0.3 × 0.024 in. 99.5% alumina.
3. Reference SOA curve.

ON Semiconductor®

COLLECTOR
3

1
BASE

2
EMITTER
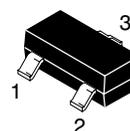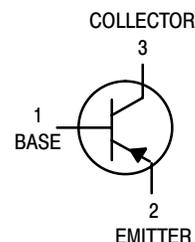
SOT-23 (TO-236AB)
CASE 318
STYLE 6

MARKING DIAGRAM

2F M ■

1

2F = Device Code
M = Date Code*
■ = Pb-Free Package
(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
MMBT2907ALT1	SOT-23	3000 Tape & Reel
MMBT2907ALT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
MMBT2907ALT3	SOT-23	10,000 Tape & Reel
MMBT2907ALT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBT2907ALT1

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage (Note 4) (I_C = –1.0 mAdc, I_B = 0) (I_C = –10 mAdc, I_B = 0)	$V_{(BR)CEO}$	 –60 –60	 – –	Vdc
Collector–Base Breakdown Voltage (I_C = –10 μAdc, I_E = 0)	$V_{(BR)CBO}$	–60	–	Vdc
Emitter–Base Breakdown Voltage (I_E = –10 μAdc, I_C = 0)	$V_{(BR)EBO}$	–5.0	–	Vdc
Collector Cutoff Current (V_{CE} = –30 Vdc, $V_{EB(off)}$ = –0.5 Vdc)	I_{CEX}	–	–50	nAdc
Collector Cutoff Current (V_{CB} = –50 Vdc, I_E = 0) (V_{CB} = –50 Vdc, I_E = 0, T_A = 125°C)	I_{CBO}	 – –	 –0.010 –10	μAdc
Base Cutoff Current (V_{CE} = –30 Vdc, $V_{EB(off)}$ = –0.5 Vdc)	I_{BL}	–	–50	nAdc
ON CHARACTERISTICS				
DC Current Gain (I_C = –0.1 mAdc, V_{CE} = –10 Vdc) (I_C = –1.0 mAdc, V_{CE} = –10 Vdc) (I_C = –10 mAdc, V_{CE} = –10 Vdc) (I_C = –150 mAdc, V_{CE} = –10 Vdc) (I_C = –500 mAdc, V_{CE} = –10 Vdc) (Note 4)	h_{FE}	 75 100 100 100 50	 – – – 300 –	–
Collector–Emitter Saturation Voltage (Note 4) (I_C = –150 mAdc, I_B = –15 mAdc) (Note 4) (I_C = –500 mAdc, I_B = –50 mAdc)	$V_{CE(sat)}$	 – –	 –0.4 –1.6	Vdc
Base–Emitter Saturation Voltage (Note 4) (I_C = –150 mAdc, I_B = –15 mAdc) (I_C = –500 mAdc, I_B = –50 mAdc)	$V_{BE(sat)}$	 – –	 –1.3 –2.6	Vdc
SMALL–SIGNAL CHARACTERISTICS				
Current–Gain–Bandwidth Product (Notes 4, 5), (I_C = –50 mAdc, V_{CE} = –20 Vdc, f = 100 MHz)	f_T	200	–	MHz
Output Capacitance (V_{CB} = –10 Vdc, I_E = 0, f = 1.0 MHz)	C_{obo}	–	8.0	pF
Input Capacitance (V_{EB} = –2.0 Vdc, I_C = 0, f = 1.0 MHz)	C_{ibo}	–	30	
SWITCHING CHARACTERISTICS				
Turn–On Time	(V_{CC} = –30 Vdc, I_C = –150 mAdc, I_{B1} = –15 mAdc)	t_{on}	–	45	
Delay Time		t_d	–	10	
Rise Time		t_r	–	40	ns
Turn–Off Time	(V_{CC} = –6.0 Vdc, I_C = –150 mAdc, I_{B1} = I_{B2} = –15 mAdc)	t_{off}	–	100	
Storage Time		t_s	–	80	
Fall Time		t_f	–	30	

4. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
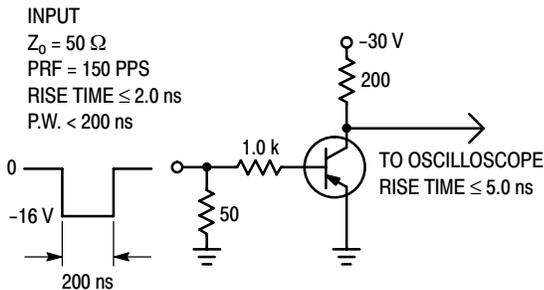5. f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.

INPUT
Z_0 = 50 Ω
PRF = 150 PPS
RISE TIME ≤ 2.0 ns
P.W. < 200 ns

–30 V
200
1.0 k
50
TO OSCILLOSCOPE
RISE TIME ≤ 5.0 ns
0
–16 V
200 ns

Figure 1. Delay and Rise Time Test Circuit

INPUT
Z_0 = 50 Ω
PRF = 150 PPS
RISE TIME ≤ 2.0 ns
P.W. < 200 ns

+15 V   –6.0 V
1.0 k   37
1.0 k
50   1N916
TO OSCILLOSCOPE
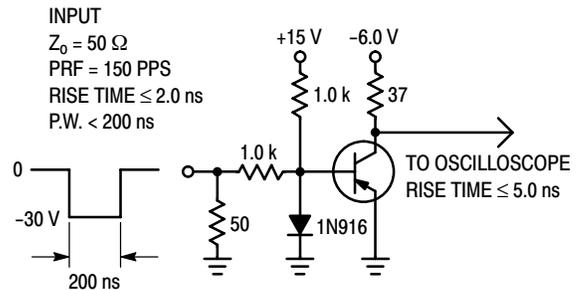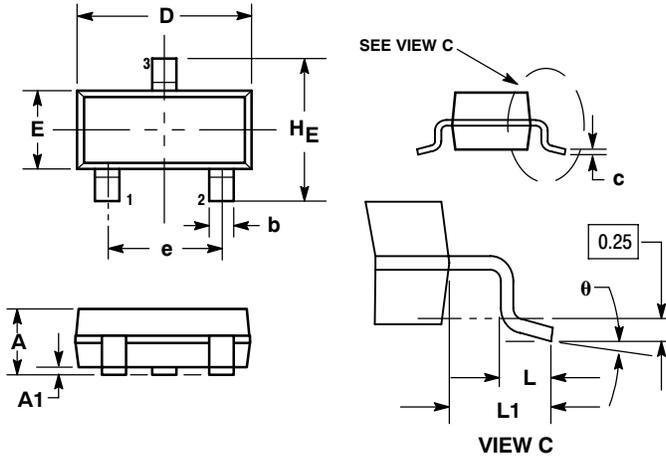RISE TIME ≤ 5.0 ns
0
–30 V
200 ns

Figure 2. Storage and Fall Time Test Circuit

MMBT2907ALT1

PACKAGE DIMENSIONS

SOT–23 (TO–236)
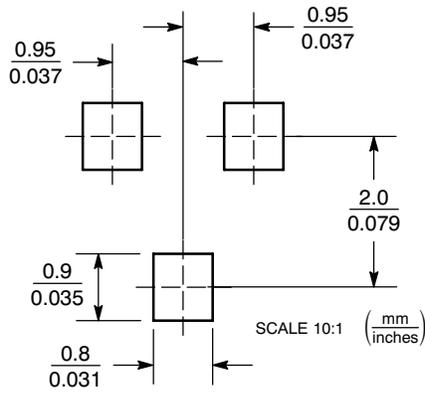CASE 318–08
ISSUE AN

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318–01 THRU –07 AND –09 OBSOLETE, NEW STANDARD 318–08.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
H$_E$	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:
PIN 1. BASE
    2. EMITTER
    3. COLLECTOR

SEE VIEW C

VIEW C

SOLDERING FOOTPRINT*

$\frac{0.95}{0.037}$

$\frac{0.95}{0.037}$

$\frac{2.0}{0.079}$

$\frac{0.9}{0.035}$

$\frac{0.8}{0.031}$

SCALE 10:1 $\left(\frac{mm}{inches}\right)$

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.